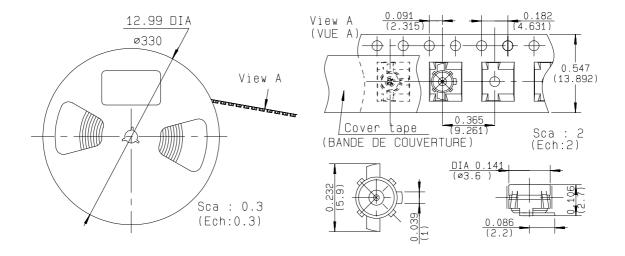
SMT TYPE - GOLD 0.2 - REEL OF 3000

R210.408.302

Series: MMT



All dimensions are in mm.



COMPONENTS	MATERIALS	PLATINGS (μm)
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS -	PHOSPHOR BRONZE BRASS PHOSPHOR BRONZE PTFE	GOLD 0.2 OVER NICKEL 2 GOLD 0.2 OVER NICKEL 2 GOLD 0.2 OVER NICKEL 2

Issue: 0325 C

In the effort to improve our products, we reserve the right to make changes judged to be



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PACKAGING

Standard	Unit	Other
3000	•	Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-8} \;\; \text{GHz} \end{array}$

VSWR 1.10 + 0.050 x F(GHz) Maxi

Insertion loss 0.20 VF(GHz) in Maxi

RF leakage - (**NA** - F(GHz)) dB Maxi

Voltage rating 170 Veff Maxi Dielectric withstanding voltage 1800 Veff mini Insulation resistance 1900 M Ω mini

ENVIRONMENTAL

Operating temperature -55/+100 ° C

Hermetic seal **NA** Atm.cm3/s

Panel leakage NA

OTHERS CHARACTERISTICS

Assembly instruction

Others:

accouplt: 18Nmax / desacc.: 7Nmin

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

NA N mini
NA N mini
NA N.cm mini

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 500 Cycles mini

Weight **0.100** g

Issue: 0325 C

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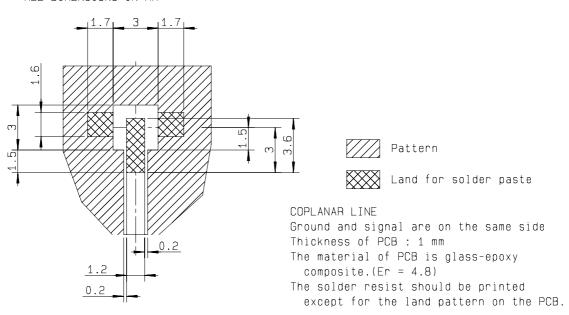
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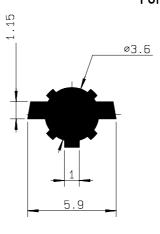
MMT SERIES - INFORMATION

ALL DIMENSIONS IN MM



ALL DIMENSIONS IN MM

SHADOW OF MMT RECEPTACLE FOR VIDEO CAMERA



Issue: 0325 C

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R210.408.302

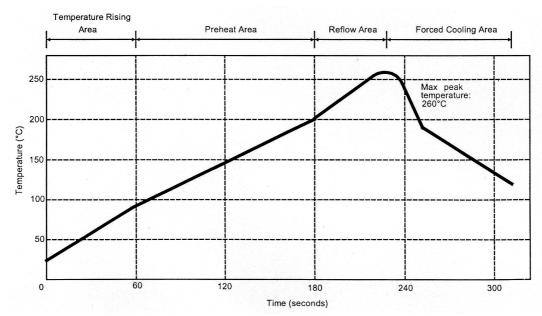
SMT TYPE - GOLD 0.2 - REEL OF 3000

Series: MMT

SOLDER PROCEDURE OF MMT RECEPTACLE IN INDUSTRIAL ENVIRONMENT

- 1 Deposition of solder paste Sn Ag4 Cu0.5 on mounting zone by screen printing application. We recommend a Low Residue Solid Flux.
 - We advise a thickness of 200 microns (7.800 microinches). Verify that the edges of the printed zone are clean.
- 2 Placement of the receptacle on the mounting zone with an automatic machine of « pick and place » type. A video camera is recommanded for positioning of the component. (see page 3) Adhesive agents must not be used on the receptacle.
- 3 Soldering by infra-red reflow. Below, please find the typical profile to use.
- 4 Cleaning of printed circuit boards
- 5 Verification of solder joints and position of the component by visual inspection

Note: The MMT receptacle and the MMT plug must not be mated before completion of this procedure.



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0325 C

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necessary.

